

AMENDMENTS TO THE SPECIFICATION

Please insert the following paragraph at page 1, line 3:

CROSS-REFERENCE TO RELATED APPLICATIONS

The present application is a continuation of PCT application PCT/CA02/01366 filed on September 10, 2002 designating the United States of America and currently pending, which also claims priority of US provisional application number 60/317,969, filed on September 10, 2001.

Please replace the paragraph at page 6, line 16 with the following amended paragraphs:

According to a first broad aspect of the present invention, there is provided a method for trimming a functional resistor, the method comprising: ~~providing a thermally isolated micro platform on a substrate;~~ placing a plurality of thermally-trimmable functional resistors on the thermally isolated micro platform a substrate; and subjecting a portion of the ~~thermally isolated micro platforms~~ substrate to a heat pulse such that a resistance value of one of said plurality of functional resistors is trimmed while a resistance value of remaining ones of said plurality of functional resistors remains substantially untrimmed.

Preferably, a thermally isolated micro platform is provided on the substrate and the plurality of thermally-trimmable functional resistors are placed on the thermally isolated micro platform.

Please replace the paragraph at page 7, line 22 with the following amended paragraphs:

According to a second broad aspect of the present invention, there is provided a method for providing and trimming a circuit, the method comprising: ~~providing at least one thermally isolated micro platform on a substrate;~~ placing at least two resistive elements with non-zero temperature induced drift on ~~said at least one thermally isolated micro platform~~ a substrate to be thermally isolated, such that said at

least two resistive elements ~~on said at least one micro-platform~~ are subjected to a substantially same operating environment, at least one of said at least two resistive elements ~~on said at least one micro-platform~~ being thermally trimmable; trimming said at least one resistive element ~~on said at least one micro-platform~~ to trim said circuit by thermal cycling; connecting said at least two resistive elements together in said circuit in a manner to compensate for said operating environment ~~on said at least one micro-platform~~; wherein heat generated during operation on the at least one micro-platform is distributed among said at least two resistive elements such that temperature drift is substantially compensated.

Preferably, at least one thermally-isolated micro-platform is provided and the at least two resistive elements are placed on the thermally-isolated micro-platform.

Please replace the paragraph at page 8, line 5 with the following amended paragraphs:

According to a third broad aspect of the present invention, there is provided a method for trimming a functional resistor, the method comprising: ~~providing a thermally-isolated micro-platform on a substrate~~; placing a functional resistor on said ~~thermally-isolated micro-platform~~ substrate; subjecting said functional resistor to a heat source having a power dissipation geometry adapted to obtain a substantially constant temperature distribution across said functional resistor when a temperature of said functional resistor is raised for trimming purposes; and trimming said functional resistor using at least one heat pulse.

Preferably, a thermally-isolated micro-platform is provided on the substrate and the functional resistor is placed on the thermally-isolated micro-platform.

Please replace the paragraph at page 9, line 14 with the following amended paragraphs:

According to a seventh broad aspect of the present invention, there is provided a method for calculating a temperature coefficient of resistance of a functional resistor, the method comprising: ~~providing at least one thermally-isolated micro-~~

~~platform on a substrate; placing a functional resistor on said at least one thermally-isolated micro-platform~~ a substrate to be thermally isolated; heating said functional resistor; measuring a resistance value of said functional resistor at ambient temperature and at an elevated temperature; and calculating said temperature coefficient of resistance based on said measured resistance values.

Preferably, at least one thermally-isolated micro-platform is provided and the functional resistor is placed on the at least one thermally-isolated micro-platform.